

N-Channel 60-V (D-S) MOSFET

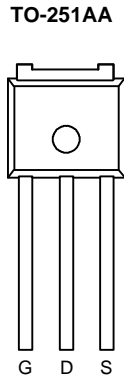
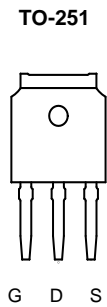


RoHS
COMPLIANT

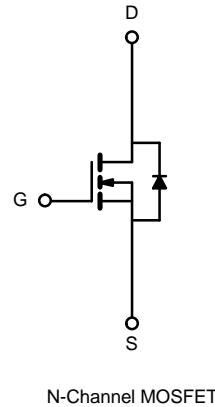
PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
60	0.016 @ $V_{GS} = 10$ V	40

FEATURES

- DT-Trench Power MOSFET
- 175°C Maximum Junction Temperature
- 100% R_g Tested



Top View



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 175^\circ\text{C}$) ^b	I_D	$T_C = 25^\circ\text{C}$	A
		$T_C = 125^\circ\text{C}$	
Pulsed Drain Current	I_{DM}	120	
Continuous Source Current (Diode Conduction)	I_S	40	
Avalanche Current	I_{AR}	40	mJ
Repetitive Avalanche Energy (Duty Cycle $\leq 1\%$)	E_{AR}	80	
Maximum Power Dissipation	P_D	$T_C = 25^\circ\text{C}$	W
		$T_A = 25^\circ\text{C}$	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 175	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Junction-to-Ambient ^a	R_{thJA}	$t \leq 10$ sec	15	$^\circ\text{C}/\text{W}$
		Steady State	40	
Junction-to-Case	R_{thJC}	0.85	1.1	

Notes

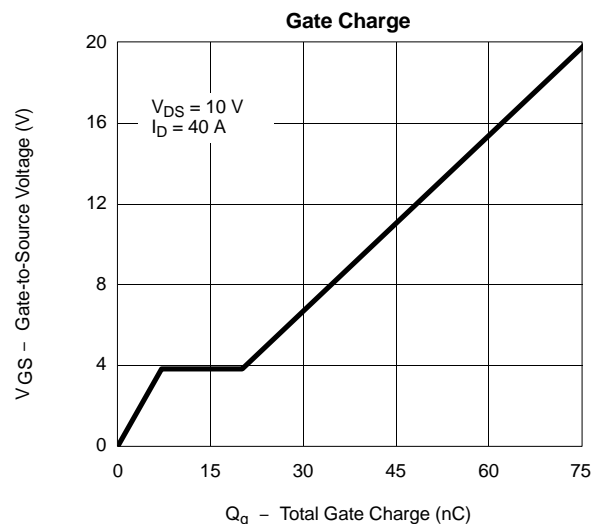
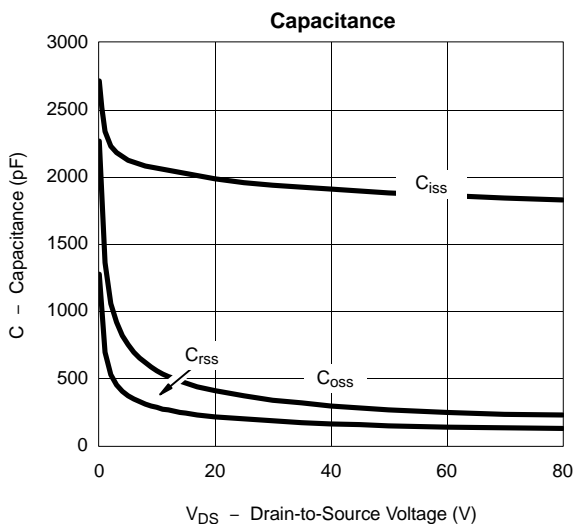
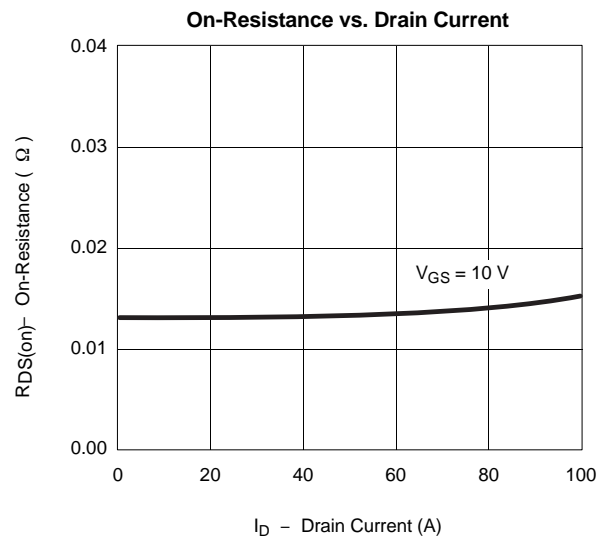
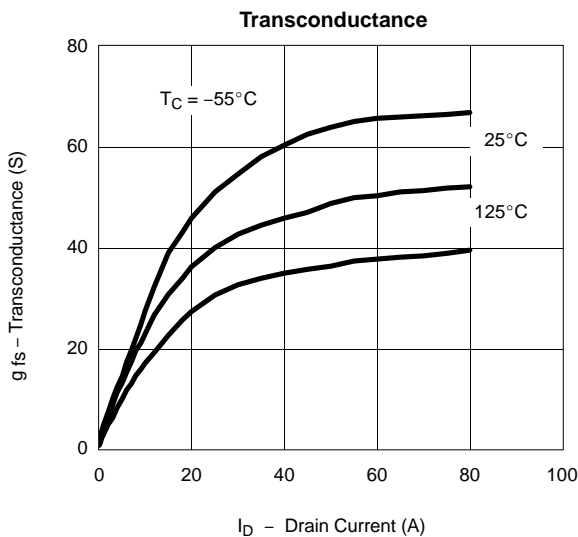
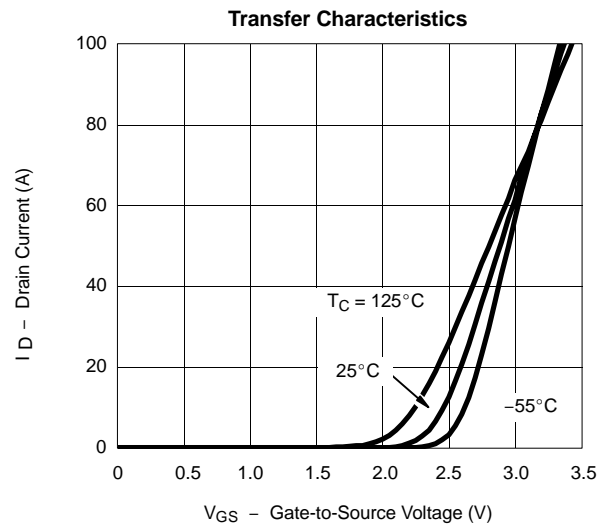
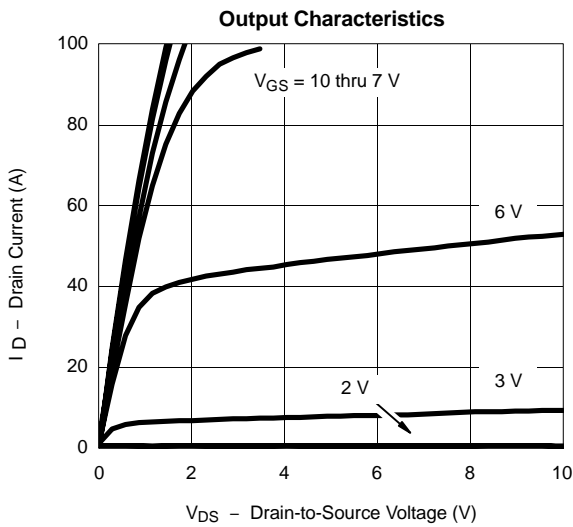
- a. Surface Mounted on 1" x 1" FR4 Board.
b. See SOA curve for voltage derating.

SPECIFICATIONS (T _J = 25 °C UNLESS OTHERWISE NOTED)						
Parameter	Symbol	Test Condition	Min	Typ ^a	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 250 μA	60			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1.0		3.0	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V			1	μA
		V _{DS} = 60 V, V _{GS} = 0 V, T _J = 125 °C			50	
		V _{DS} = 60 V, V _{GS} = 0 V, T _J = 175 °C			250	
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	40			A
Drain-Source On-State Resistance ^b	r _{DS(on)}	V _{GS} = 10 V, I _D = 40 A		0.013	0.016	Ω
		V _{GS} = 10 V, I _D = 40 A, T _J = 125 °C			0.027	
		V _{GS} = 10 V, I _D = 40 A, T _J = 175 °C			0.037	
Forward Transconductance ^b	g _{fs}	V _{DS} = 15 V, I _D = 40 A		45		S
Dynamic^a						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, F = 1 MHz		1960		pF
Output Capacitance	C _{oss}			370		
Reverse Transfer Capacitance	C _{rss}			200		
Total Gate Charge ^c	Q _g	V _{DS} = 40 V, V _{GS} = 10 V, I _D = 40 A		42	60	nC
Gate-Source Charge ^c	Q _{gs}			7		
Gate-Drain Charge ^c	Q _{gd}			13		
Gate Resistance	R _g		0.5		2.7	Ω
Turn-On Delay Time ^c	t _{d(on)}	V _{DD} = 40 V, R _L = 1.0 Ω I _D = 40 A, V _{GEN} = 10 V, R _g = 2.5 Ω		12	20	ns
Rise Time ^c	t _r			52	80	
Turn-Off Delay Time ^c	t _{d(off)}			25	38	
Fall Time ^c	t _f			10	15	
Source-Drain Diode Ratings and Characteristic (T_C = 25 °C)						
Pulsed Current	I _{SM}				120	A
Diode Forward Voltage ^b	V _{SD}	I _F = 40 A, V _{GS} = 0 V		1.0	1.5	V
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 40 A, di/dt = 100 A/μs		45	70	ns

Notes

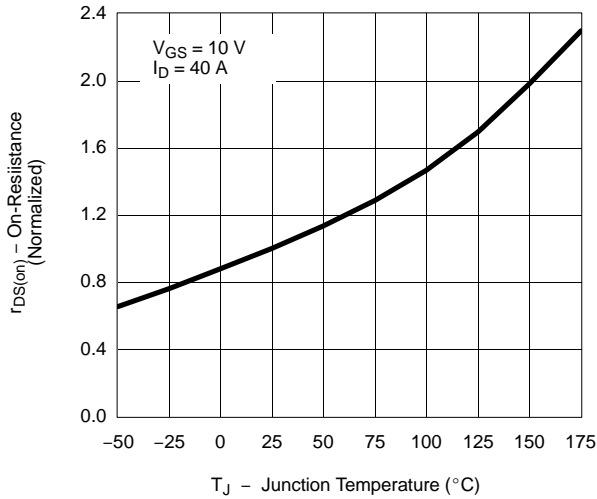
- Guaranteed by design, not subject to production testing.
- Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
- Independent of operating temperature.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

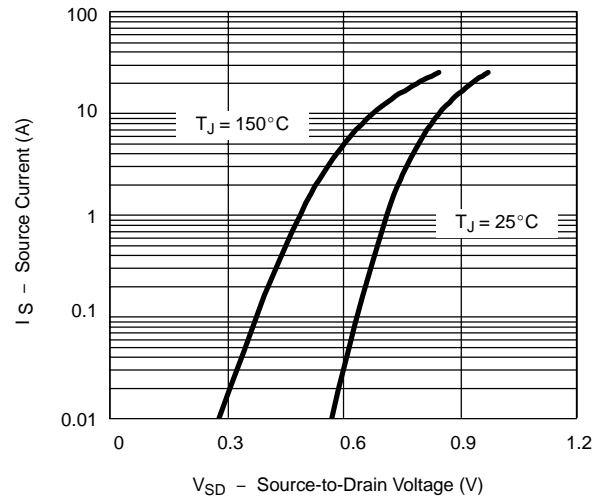


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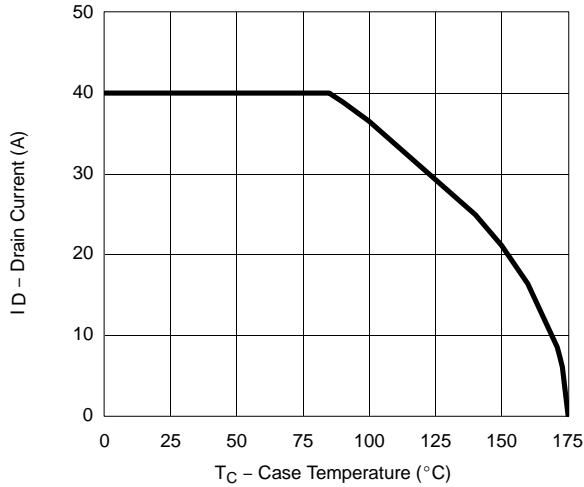
On-Resistance vs. Junction Temperature



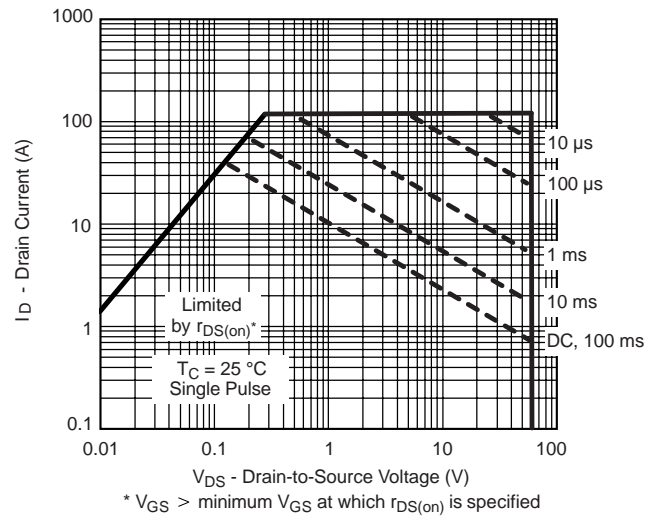
Source-Drain Diode Forward Voltage



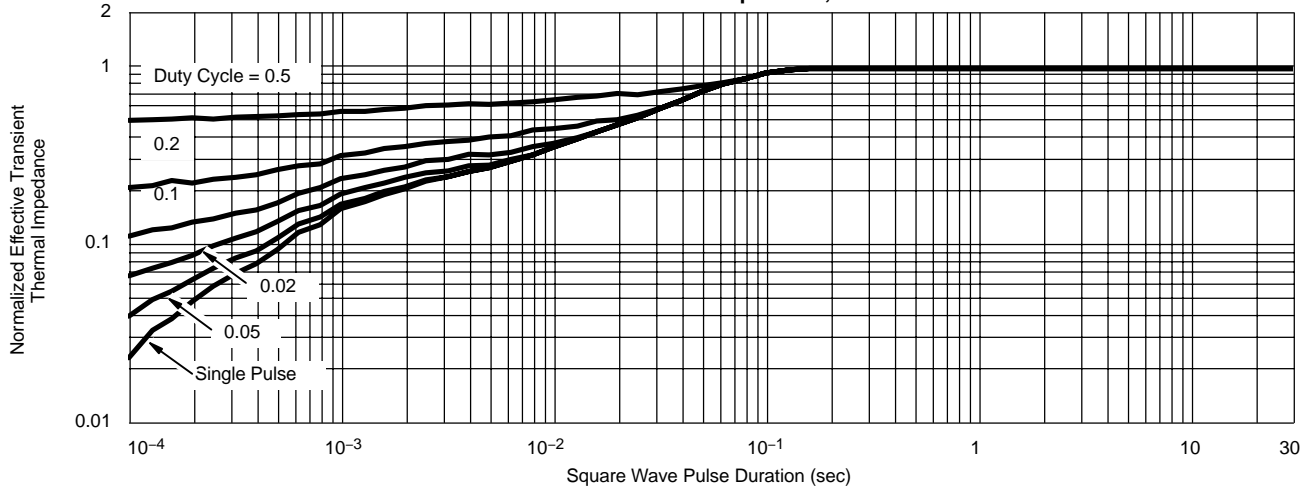
Maximum Avalanche Drain Current vs. Case Temperature



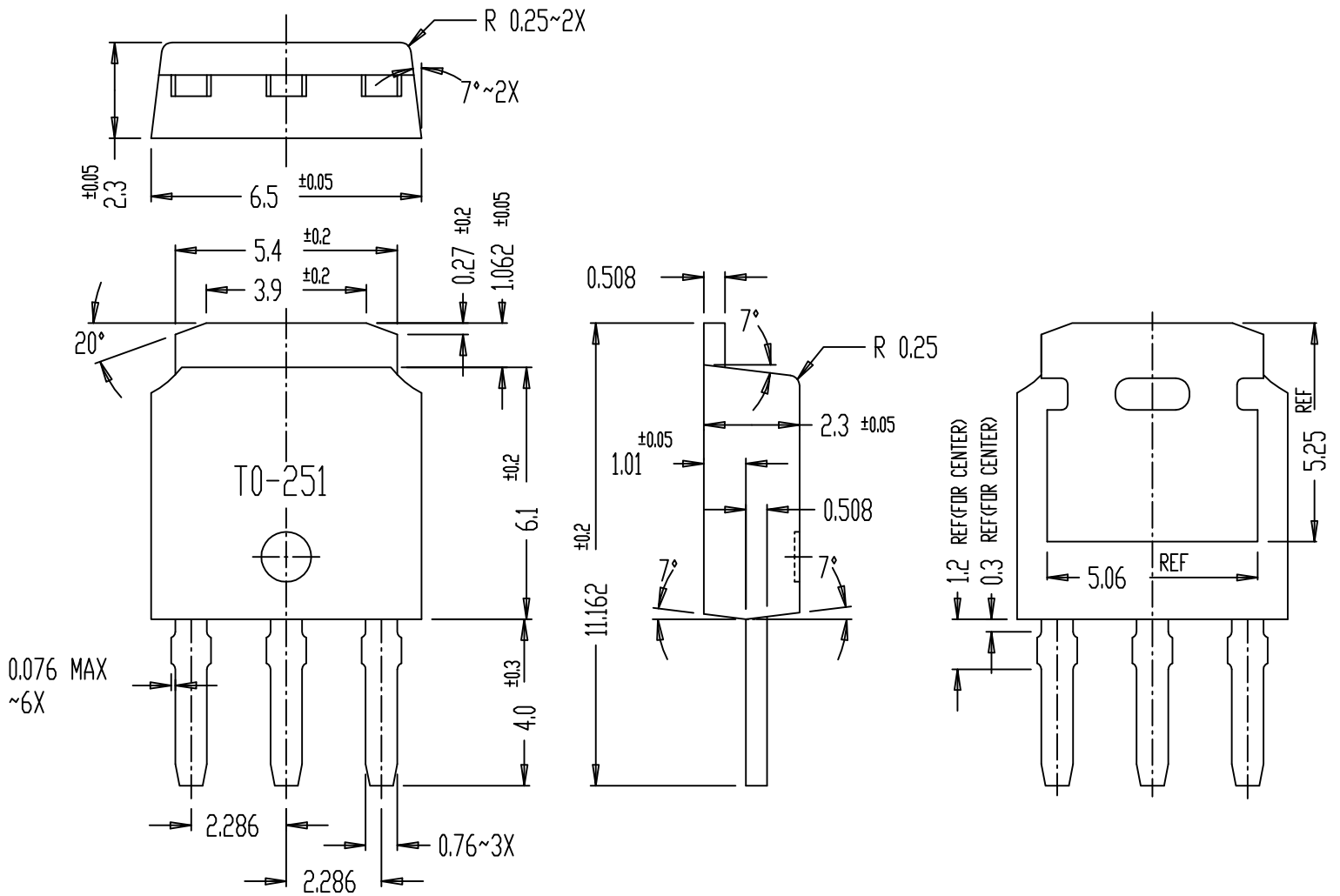
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case



TO-251 Outline



TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	2.21	2.38	0.087	0.094
A1	0.89	1.14	0.035	0.045
b	0.71	0.89	0.028	0.035
b1	0.76	1.14	0.030	0.045
b2	5.23	5.43	0.206	0.214
c	0.46	0.58	0.018	0.023
c1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
E	6.48	6.73	0.255	0.265
e	2.28 BSC		0.090 BSC	
L	8.89	9.53	0.350	0.375
L1	1.91	2.28	0.075	0.090
L2	0.89	1.27	0.035	0.050
L3	1.15	1.52	0.045	0.060
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346				

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